# Semicustom

**Bi-CMOS** 

# **ASTRO-NT** (for RF front-end LSI-Based on PLL, Analog Macro)

# **MB15G000 Series**

### DESCRIPTION

The ASTRO-NT\* is a new technology to correspond to the demand of high performance RF LSI. The technology stands on a macro concept and create a custom LSI ideal for use in high frequency front-end circuit such as VCO, amplifier, mixer and I/Q modulator devices.

The chip can be built by combining macros, in accordance with user's demand function and characteristic. FUJITSU prepares standard RF macros. They are well finished in design and layout to fulfil good performance by function that a master slice method can not achive. It is possible to modify RF macro in response to user's demand.

This LSI series uses FUJITSU's latest BiCMOS process technology for low current consumption. In addition, many types of packages are available that makes it possible to find a proper size package for different circuit integration levels.

ASTRO-NT is ideal for applications with RF or IF signal, particularly mobile communication devices operating such as PDC, PHS, GSM, DCS, PCS and so on.

\*: Advanced Standard macro base Technology of PLL with RF system On LSI-New Technology

### FEATURES

- High operating frequency: to 3.0 GHz (max)
- Supply voltage: 2.5 to 5.5 V
- Standard RF macro
- Low power consumption
- Package line up –Many types of package are available.

SSOP-16, SSOP-20, SSOP-24, SSOP-34, BCC-16, BCC-48, LQFP-48, LQFP-64,

- Operating temperature: -40 to +85°C
- · Fujitsu's latest BiCMOS process technology

### ■ PACKAGES



Number of pins and name of package	Package Code	Size (mm)
16-pin Plastic SSOP	FPT-16P-M05	$6.4 \times 5.0 \times 1.25$
20-pin Plastic SSOP	FPT-20P-M03	6.4 imes 6.5 imes 1.25
24-pin Plastic SSOP	FPT-24P-M03	$7.6\times7.75\times1.25$
34-pin Plastic SSOP	FPT-34P-M03	$8.1\times11.0\times1.25$
48-pin Plastic LQFP	FPT-48P-M05	9.0 imes9.0 imes1.5
64-pin Plastic LQFP	FPT-64P-M03	$12.0\times12.0\times1.5$
16-pad Plastic BCC	LCC-16P-M02	$3.4 \times 4.55 \times 0.8$
To-pau Flastic DCC	LCC-16P-M03	$4.2\times4.55\times0.8$
48-pad Plastic BCC	LCC-48P-M02	7.0  imes 7.0  imes 0.8

### ABSOLUTE MAXIMUM RATINGS

Baramatar	Symbol	Rat	Unit	
Faiameter	Symbol	Min.	Max.	Unit
Power supply veltage *1	Vcc *2	-0.5	4.0	V
Fower supply voltage	Vcc *3	-0.5	6.0	V
Input voltage *1	Vin	-0.5	Vcc + 0.5	V
Output current	lout	-10	10	mA
Storage temperature	Tstg	-55	+125	°C

\*1:Voltage values are based on GND = 0 V

\*2:Using 3V macro specifications

\*3:Using 5V macro specifications

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

### RECOMMENDED OPERATING CONDITIONS

Paramotor	Symbol		Unit		
Falameter	Symbol	Min.	Тур.	Max.	Unit
	Vcc *2,*3	2.7	3.0	3.3	V
Power supply voltage *1	Vcc *2,*4	4.5	5.0	5.5	V
	GND	—	0	—	V
Input voltage	Vin	GND	—	Vcc	V
Operating temperature	Та	-40	—	+85	О°

\*1:Voltage values are based on GND = 0 V

\*2: The range of operating voltage should be defined depends on circuit configuration. For models not using standard 3V or 5V specifications, maximum ratings and recommended operating conditions are set according to circuit use.

\*3:Using 3V macro specifications

\*4:Using 5V macro specifications

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

### MACRO DESCRIPTIONS

#### 1. Prescaler

Divides the reference frequency by any given value and outputs the resulting frequency. Choice of two -modulus or fixed output mode.

#### 2. PLL

#### • Phase comparator

The phase comparator has a phase detection range of  $-2\pi$  to  $+2\pi$ , and is designed to eliminate blind spots in phase comparison by output of a margin-of-error signal to the charge pump even when the phase difference is zero. Phase comparator characteristics can also be tuned to the polarity of VCO.

#### Counters

The divide ratios of the comparator-side counter and reference-side counter can be either programmable or fixed.

#### Charge pump

The "H" level output voltage from the charge pump is determined by power supply voltage. Charge pump characteristics for the sending and receiving systems can be optimized for each specific application.

For example, when FM modulation is applied directly to the VCO signal, charge pump characteristic can be adjusted for lower speeds in order to reduce the sensitivity of the synthesizer loop so that output does not track the modulation.

#### High speed lock-up circuit

This circuit is specially designed for faster lock-up speeds.

#### Intermittent operation control circuit

This on-chip power-saving function reduces circuit current flow in standby status, enabling devices to operate with less power demand. A special circuit is built in to prevent excessive error signal from increasing lock-up delay during the transition from power-saving mode to operating mode.

#### List of standard macros

Туре	Vcc	lcc	Operating frequency	Prescaler divide ratio (M)	Comparator counter divide ratio (N)	Swallow counter divide ratio (A)	Reference counter divide ratio (R)
PLL1		1.5 mA	0.5 GHz	8/9, 16/17			
PLL2	271	2.0 mA	1.2 GHz		5 to 2047	0 to 255	5 to 16383
PLL3	2.7 V	3.0 mA	2.0 GHz	32/33, 64/65			
PLL4		3.5 mA	2.5 GHz				

Crystal oscillator input frequency: Up to 32 MHz

Standby mode current demand: 10 µA(Max.)

Note: Refer to macro specification book.

### 3. RF Analog Macro List

Circuit	Function		Voltage	Current	Application Example	
	900 MHz QMOD + AGC			29.6 mA	PDC	
	1.9 GHz MOD + UpCONV (IF =	= 233 MHz)		27.0 mA	PHS	
	0.9, 1.9 GHz Doubler + MOD U	CONV IF = 413 MHz	3.0 V	28.0 mA	GSM/DCS, PCS	
QMOD/QDEM	130 MHz Shifter QMOD			7.7 mA	CDMA	
	85 MHz Shifter + QDEM			7.8 mA	CDMA	
	Offset Mix + QMOD + AGC (90	0 MHz)	2.9 V	39.0 mA	PDC	
	VCO + QMOD + AGC (200 MH	lz)		22.0 mA	CDMA	
	Lo = 250 MHz, IF = 10.8 MHz 2	2nd Mixer		3.5 mA	PHS	
2nd Mixor	Lo = 130 MHz, IF = 450 kHz 2r	nd Mixer		3.0 mA	PDC	
	400 MHz IF AMP + 2nd Mixer			5.0 mA	GSM/DCS, PCS	
	800 MHz, 1.9 GHz UpCONV		3.0 V	10.2 mA	CDMA	
	1.3-1.6 GHz Local Buffer AMP		3.0 mA	GSM/DCS, PCS		
	400 MHz VCO + VCO Buffer		5.0 mA	GSM/DCS, PCS		
Bul Alvir/VCO	260 MHz VCO (Tx)		3.0 mA	CDMA		
	170 MHz VCO (Rx)		1.6 mA	CDMA		
	450 KHz LimAMP/RSSI		201/	2.0 mA	PDC	
LIIII AIVIF/KSSI	10.8 MHz LimAMP/RSSI	3.0 V	2.0 mA	PHS		
		$G_P = 40 \text{ dB}$	261	19.0 mA		
AGC AMP		G <sub>P</sub> = 55 dB	3.0 V	4.9 mA		
	850 MHz, 19 GHz AGC + Powe	er driver	3.0 V	38.5 mA	CDMA	

Note: Circuit format and other details can be adjusted to meet customer requirements.

Refer to macro specification book.

### MACRO BROCHURE

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A macro brochure is available for the convenience of customers using standard FUJITSU macros in Astro-NT development. Astro-NT can be arranged in a variety of configurations using combinations of macros. Customer may select the macros that suit their particular requirements for specifications and characteristics. Also, standard macros may be modified to meet more detailed customer requirements. The macro brochure includes sample applications and electrical characteristics of macros.

Т

 Macro Brochure (Sample Macro Electrical Characteristics) RV001QMOD (900 MHz Doubler QMOD + AGC)

Т

(Vcc = 3.0 V, Ta = -25 °C)

Baramatar	Symbol	Та	Target Value		Unit	Commoné	Condition	
Farameter	Symbol	Min.	Тур.	Max.	Unit	Comment	Condition	
Lo input frequency	fMODLO	870	948	960	MHz	-	_	
Lo input level	PMODLO	-23	-20	-15	dBm	-		
I/Q input frequency	fBB	DC		0.5	MHz	-		
I/Q input amplitude	VBB	0.5	1.0	1.2	Vpp	Single ended input		
I/Q offset voltage	VOS	1.4	1.5	1.6	V	External offset voltag	e value	
I/Q offset current	IOS		10	20	μΑ	-		
AGCcnt input voltage	AGCcnt	0.7		2.5	V	-		
SSB maximum output level	Pout1	-1.0	2.0		dBm	AGCcnt = 2.5 V		
SSB minimum output	Dout2	-32	—		dBm	AGCcnt = 1.1 V	fMODLO = 948 MHz	
level	T OULZ			-32	dBm	AGCcnt = 0.7 V	I/Q : sin, cos wave	
Carrier leakage	CL		—	-30	dBc		5.25 kHz VBB = 1.0 V Single ended	
Image rejection	IR			-30	dBc			
Third order intermodu- lation distortion	IM	_	_	-35	dBc			
Vector error	EVM	_	3.0	5	%	AGCcnt = 0.7 to 2.5V		
Amplitude error	Aerr				%			
Phase error	Perr		1.5	_	deg		PMODLO = -20  dBm	
Adjacent cannel leak-			-65 *1	-60 *1	dB			
age power	ACF		-73 *2	-68 *2	dB			
TXout1-2 isolation	ISOout		30	—	dB	-		
Power supply current	Icc		35		mA	-		

\*1:50 kHz offset

\*2:100 kHz offset

\*: Macro brochures are available by contacting your Fujitsu marketing representative.

### ■ DEVELOPMENT FLOW

Products are developed through the following processes. The illustration below shows the development flow.

#### (1) Customer Request (Phase 1)

The customer selects an existing macro from the Fujitsu Macro Brochure, for the purpose of producing a system block in a specific design. If the desired macro does not exist, the customer may request Fujitsu to modify an existing macro.

#### (2) Functional Study and Price Approximation (Phase 2)

Based on the customer request, Fujitsu and the customer make an initial study of feasibility. An initial price estimate is also made.

#### (3) Development Start (Phase 3)

Based on the results of the primary study, and with the approval of the customer, Fujitsu starts the development process. Detailed investigation is made including circuit study and simulation of circuit characteristics, a layout is created, and provisional delivery characteristics (target specifications) are drawn up. The development schedule, development costs, and price estimate are prepared.

#### (4) Prototyping and Mass Production

Based on the provisional delivery specifications approved by the customer, the LSI is designed and prototyped. The standard time for ES prototyping is approximately nine weeks. Fujitsu and the customer jointly evaluate the ES based on the provisional specifications. If no problems are found, final delivery specifications are approved and development is completed. The next step, transition to mass production and delivery, requires a standard interval of approximately three months.

• Development Flow



#### ■ PACKAGE DIMENSIONS



















### ■ ASTRO-NT REQUEST SHEET (Example)

Customer nam	e :			
Application	:			
Time	:ES;	CS;		
Quantity	:			
Macro na	ame (*1)		Use current specifications	Modification requested (*2)
RV001	AMP		×	
RV002	2MIX			×
RV0010	QMOD			X

If Modification is Requested:

Macro name : RV002MIX, RV001QMOD

Function	Parameter	Deremeter Sumk		Target Value		Unit	Commont/Condition
Block		Symbol	Min.	Тур.	Max.	Unit	Comment/Condition
RV002 MIX	Gaim	Gv		30		dB	
RV001 QMOD	SSB maximum output level	Pout1	-2	2		dBm	AGCcnt = 2.0 V

Block diagram (Example)



### ■ ASTRO-NT REQUEST SHEET

Customer nam	ne :			
Application	:			
Time	:ES;	CS;		
Quantity	:			
Macro n	ame (*1)		Use current specifications	Modification requested (*2)
		_		
		_		
		_		
		—		

<u>MEMO</u>

\*:Please fill in the macro name of the macro brochure.

\*:Please fill in the demand on an attached spec seat.

Macro name:

Function	Parameter	Symbol	Tar	get Va	lue	Unit	Unit	Comment/Condition
Block	i ulumotoi	Symbol	Min.	Тур.	Max.	Onit	Comment/Condition	

Block diagram


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